

EXPRESS MAIL NO.: EL 394 218 118 US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: S. Takeda et al.

Serial No.: Continuation of 08/981,702

Group Art Unit: To be assigned

Filed: Concurrently filed

Examiner: To be assigned

For: SEMICONDUCTOR DEVICE AND
PROCESS FOR FABRICATION
THEREOF

Attorney Docket No.: 7426-

New York, New York
April 5, 2000

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Please enter the following amendments and remarks into the file of the
present application.

IN THE CLAIMS

Please cancel claims 1-16.

Please add the following new claims:

A2
contd
SUB B17
A material comprising an organic die-bonding film having a
water absorption of 1.5% by volume or less.

18. A material according to claim 17, having a saturation moisture
absorption of 1.0% by volume or less.

SUB B27
19. A material according to claim 17, having a peel strength of 0.5
kgf/5 mm x 5 mm chip or higher at a stage where a semiconductor has been bonded
to a support member using said material.